BALANCED CAPACITANCE LEAD FRAME FOR INTEGRATED CIRCUITS

ABSTRACT OF THE INVENTION

A lead frame (10) is connected over an integrated circuit (40) by adhesives (42) and (44). Each lead conductor (16) and (18) of the lead frame (10) has the identical geometric area in order to provide identical capacitances. A metal shield may be provided on adhesives (42) and (44) to provide noise shielding for the integrated circuit (40).

This Sheet Has Been Replaced

